

Patent Claims

1. Implant for an intracorporal, telemetric measurement with a sensor device
5 and an inductive coil, which is connected to the sensor device via electrical connection lines being arranged on a longitudinal carrier, and a covering, by means of which the sensor device, the carrier with the connection lines and the coil are encapsulated;
characterized in that
10 the carrier (3) for the electrical connection lines (4) comprises such a rigidity that the sensor device (1) which is fixedly bonded to one carrier end, is guided by means of the carrier during implantation to the target position and held in position at the target position, and that the covering part (6) encapsulating the coil (2) is provided for a subcutaneous fastening.
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2. Implant according to claim 1,
characterized in that
the carrier (3) is arranged in an angle $<180^\circ$, especially from 60° to 120°
relative to the plane, in which the coil windings (8) of the inductive coil
20 (2) are arranged.
3. Implant according to claim 1 or 2,
characterized in that
at the carrier (3) there are provided two connection lines (4) between the
25 coil (2) and the sensor device (1).
4. Implant according to one of the claims 1 to 3,
characterized in that
the carrier (3) is formed in a flat manner.
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5. Implant according to one of the claims 1 to 4,
characterized in that
in the covering part (9) with which the carrier (3) and the electrical connection lines (4) being arranged on the carrier (3) are encapsulated there is
5 provided a stiffening foil or an armoring.
6. Implant according to one of the claims 1 to 5,
characterized in that
the carrier (3) is formed as a rod or a foil.
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7. Implant according to one of the claims 1 to 6,
characterized in that
the carrier (3) is formed as a stiffened foil, especially by camber or as carrier with a rectangular or circle-segment-like cross-section.
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8. Implant according to one of the claims 1 to 7,
characterized in that
at the end of the carrier (3) there is fastened a frame (10) in which the sensor device (1) is arranged positively fitting.
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9. Implant according to claim 8,
characterized in that
frame (10) is formed one piece with the carrier (3).
- 25 10. Implant according to one of the claims 1 to 9,
characterized in that
the carrier (3) is formed as a common carrier for the electrical connection lines (4) and the coil windings (8).
- 30 11. Implant according to one of the claims 1 to 10,
characterized in that

sensor device (1) comprises at least one pressure sensor.

12. Implant according to one of the claims 1 to 11,
characterized in that
5 the covering part (6) encapsulating the coil (2) is provided for a subcutaneous, especially epidural, positioning of the coil, wherein the sensor device has to be arranged in an interior of the brain.
13. Implant according to claim 11 or 12,
10 **characterized in that**
the encapsulating material of the covering part (7) covering the sensor device (1) is formed as a pressure transmitting medium, especially of silicon.
14. Implant according to one of the claims 1 to 13,
15 **characterized by**
its formation as intracranial measurement device, wherein the sensor device (1) is to be positioned for an intraparenchymal or intraventricular pressure measurement.